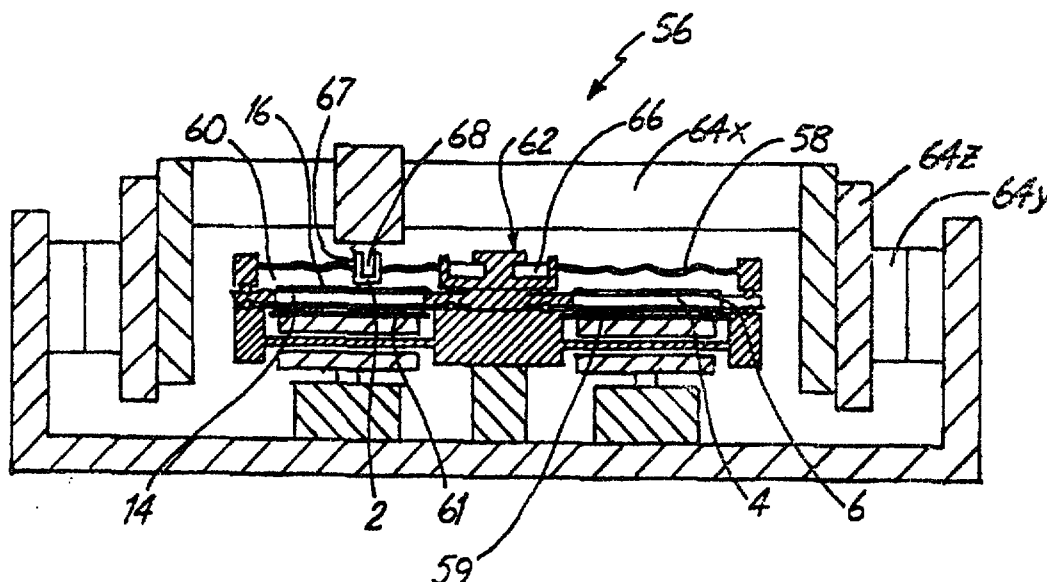


INTERNATIONAL APPLICATION PUBLISHED UNDER THE PATENT COOPERATION TREATY (PCT)

(51) International Patent Classification ⁶ : C25D 5/02, 5/10	A1	(11) International Publication Number: WO 98/45504	(43) International Publication Date: 15 October 1998 (15.10.98)
(21) International Application Number: PCT/US98/06591 (22) International Filing Date: 3 April 1998 (03.04.98) (30) Priority Data: 60/043,742 4 April 1997 (04.04.97) US (63) Related by Continuation (CON) or Continuation-in-Part (CIP) to Earlier Application US 60/043,742 (CIP) Filed on 4 April 1997 (04.04.97)		(81) Designated States: AL, AM, AT, AU, AZ, BA, BB, BG, BR, BY, CA, CH, CN, CU, CZ, DE, DK, EE, ES, FI, GB, GE, GH, GM, GW, HU, ID, IL, IS, JP, KE, KG, KP, KR, KZ, LC, LK, LR, LS, LT, LU, LV, MD, MG, MK, MN, MW, MX, NO, NZ, PL, PT, RO, RU, SD, SE, SG, SI, SK, SL, TJ, TM, TR, TT, UA, UG, US, UZ, VN, YU, ZW, ARIPO patent (GH, GM, KE, LS, MW, SD, SZ, UG, ZW), Eurasian patent (AM, AZ, BY, KG, KZ, MD, RU, TJ, TM), European patent (AT, BE, CH, CY, DE, DK, ES, FI, FR, GB, GR, IE, IT, LU, MC, NL, PT, SE), OAPI patent (BF, BJ, CF, CG, CI, CM, GA, GN, ML, MR, NE, SN, TD, TG).	
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(54) Title: ARTICLE, METHOD, AND APPARATUS FOR ELECTROCHEMICAL FABRICATION



(57) Abstract

An electroplating method that includes: a) contacting a first substrate (2) with a first electroplating article (4), which includes a support and a conformable mask disposed in a pattern on the support; b) electroplating a first metal from an electroplating bath (58) which is a source of metal ions onto the first substrate in a first pattern, the first pattern corresponding to the complement of the conformable mask pattern; and c) removing the first article from the first substrate, is disclosed. The method may be used in the microfabrication of miniaturized devices. Electroplating articles and electroplating apparatus are also disclosed.